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CuP-300 Technical Data Sheet (TDS)

Description

CuP-300 is a novel cost effective alkaline aqueous copper advanced Micro Etch formulation used in multiple copper surface prep applications. CuP-300 provides superior substrate cleaning with controlled copper roughness providing improved adhesion. CuP-300 is the second in a series of copper surface preparation family of products providing low Cu etch.

Applications

Where smooth Copper surface is required, typically at higher signal speeds greater than 20 GHz. Intended to replace Pumice Scrub processes and Persulfate based Micro Etch processes that generate too much copper roughness (pitting). Copper surface preparation takes place on multiple levels including inner layers.

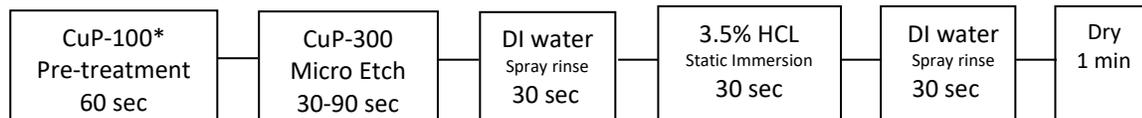
CuP-300 Benefits

1. Controlled uniform copper etch from 0.1 to 1.0 micron
2. Replace pumice scrub process
3. Improve adhesion
4. Minimum copper sludge build up in the treatment bath
5. Cu bath loading does not affect performance
6. Removes oils and greases as a pretreatment step

CuP-300 process replaces most existing POR Micro Etch and Pretreatment steps, such as:

1. Sodium Persulfate
2. Sodium Persulfate mixed with Sulfuric Acid
3. Sulfuric Acid mixed in with Peroxide

Process Recommendation: *(Suggested recipe, adjustments may be needed to meet various process specs)*



CuP-100 is CuP-100 spiked with an oxidizer to improve surface contamination removal and increase etch rate.*

Material Compatibility

High Density polyethylene (HDPE), PFA, Polypropylene, 316L Stainless steel, and Teflon (PTFE) are normally suitable materials of construction.

Handling/Storage/Shipping

Read the product MSDS before handling and using the product. CuP-300 has a twelve (12) month shelf life when stored in unopened containers. Store at 0-30° C. Open drums and diluted product must kept under a N₂ (nitrogen) blanket. CuP-300 is available in 1 gal, 2.5 gal, 5 gal and 55 gal HDPE drums.

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